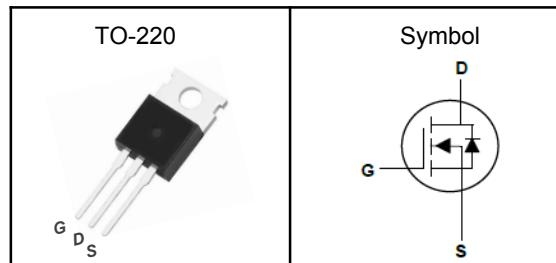


N-Channel Enhancement Mode MOSFET

Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

| | | |
|------------------|------|-----------|
| V_{DSS} | 900 | V |
| $R_{DS(ON)-Typ}$ | 1700 | $m\Omega$ |
| I_D | 6 | A |

Absolute Maximum Ratings ($T_J=25^\circ C$, Unless Otherwise Noted)

| Symbol | Parameter | Rating | Unit | |
|--------------|--|------------------|------------|---|
| V_{DSS} | Drain-Source Voltage | 900 | V | |
| V_{GSS} | Gate-Source Voltage | ± 30 | V | |
| T_J | Maximum Junction Temperature | -55 to 150 | $^\circ C$ | |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ | |
| E_{AS} | Single Pulse Avalanche Energy ^③ | 180 | mJ | |
| $I_{DM}^{①}$ | Pulse Drain Current Tested | 24 | A | |
| I_D | Continuous Drain Current | $T_c=25^\circ C$ | 6 | A |
| P_D | Maximum Power Dissipation | $T_c=25^\circ C$ | 160 | W |

Thermal Characteristics

| Symbol | Parameter | Rating | Unit |
|-----------|--|--------|--------------|
| $R_{θJA}$ | Thermal Resistance Junction-Ambient ₁ | 62.5 | $^\circ C/W$ |
| $R_{θJC}$ | Thermal Resistance Junction-Case ₁ | 0.78 | $^\circ C/W$ |

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Unit |
|--|------------------------------------|---|-----|------|-----------|------------------|
| Static Electrical Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 900 | --- | --- | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{\text{DS}}=900\text{V}$, $V_{\text{GS}}=0\text{V}$ | --- | --- | 1 | μA |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$ | 2.5 | --- | 4.5 | V |
| I_{GSS} | Gate Leakage Current | $V_{\text{GS}}=\pm 30\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| $R_{\text{DS(ON)}}$ | Drain-Source On-state Resistance | $V_{\text{GS}}=10\text{V}$, $I_D=3\text{A}$ | --- | 1700 | 2000 | $\text{m}\Omega$ |
| Dynamic Characteristics^⑤ | | | | | | |
| C_{iss} | Input Capacitance | $V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=25\text{V}$, Freq.=1MHz | --- | 1255 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 110 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 20 | --- | |
| $T_{\text{d(on)}}$ | Turn-on Delay Time | $V_{\text{DD}}=450\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=25\Omega$, $I_D=6\text{A}$ | --- | 42 | --- | nS |
| T_r | Turn-on Rise Time | | --- | 25 | --- | |
| $T_{\text{d(off)}}$ | Turn-off Delay Time | | --- | 203 | --- | |
| T_f | Turn-off Fall Time | | --- | 42 | --- | |
| Q_g | Total Gate Charge | $V_{\text{DD}}=720\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=6\text{A}$ | --- | 47 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 8 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 24 | --- | |
| Source-Drain Characteristics ($T_J=25^\circ\text{C}$) | | | | | | |
| V_{SD} | Diode Forward Voltage ^② | $V_{\text{GS}}=0\text{V}$, $I_s=3\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1.4 | V |
| t_{rr} | Reverse Recovery Time | $I_F=6\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$ | --- | 520 | --- | nS |
| Q_{rr} | Reverse Recovery Charge | | --- | 1.5 | --- | nC |

Note ④ : Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET

Typical Characteristics

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

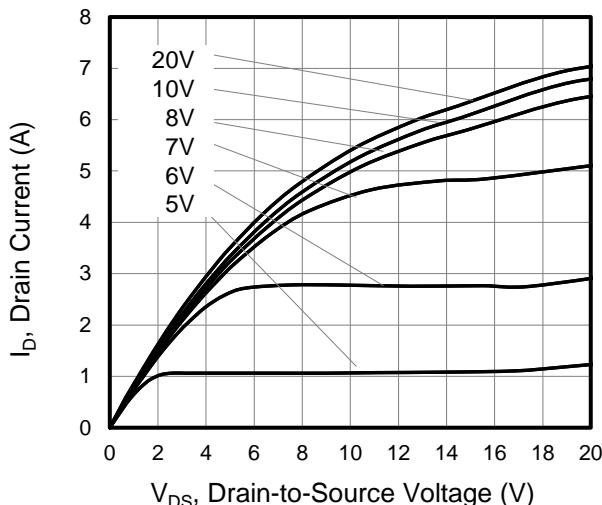


Figure 2. Body Diode Forward Voltage

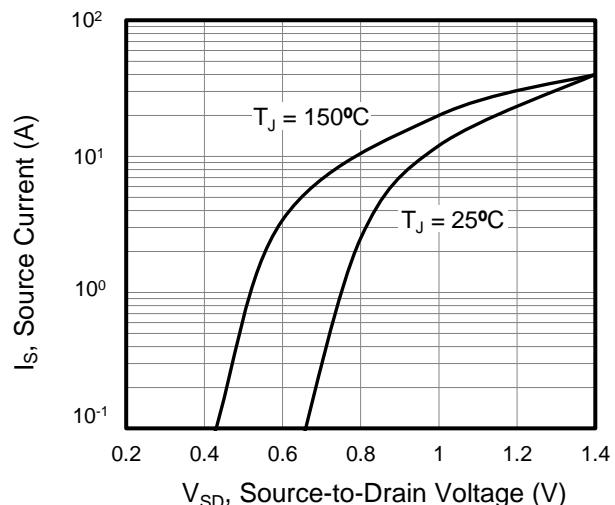


Figure 3. Drain Current vs. Temperature

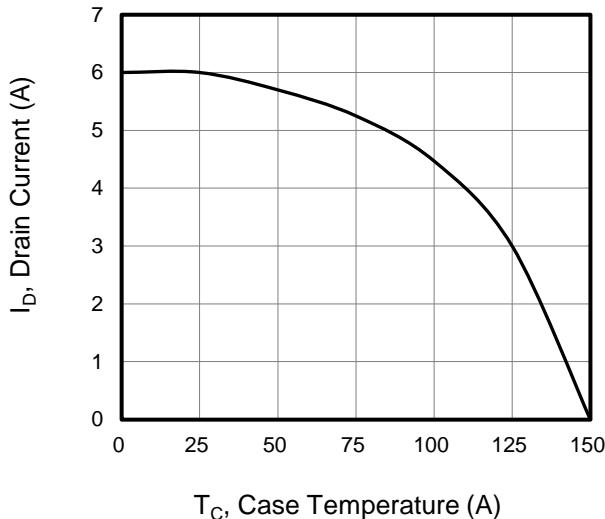


Figure 4. BV_{DSS} Variation vs. Temperature

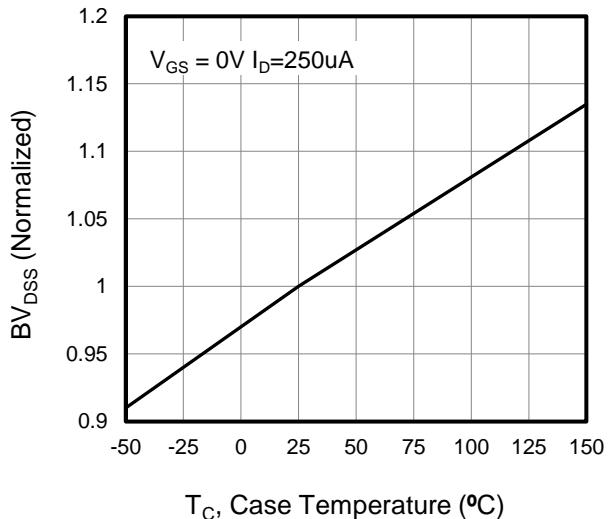


Figure 5. Transfer Characteristics

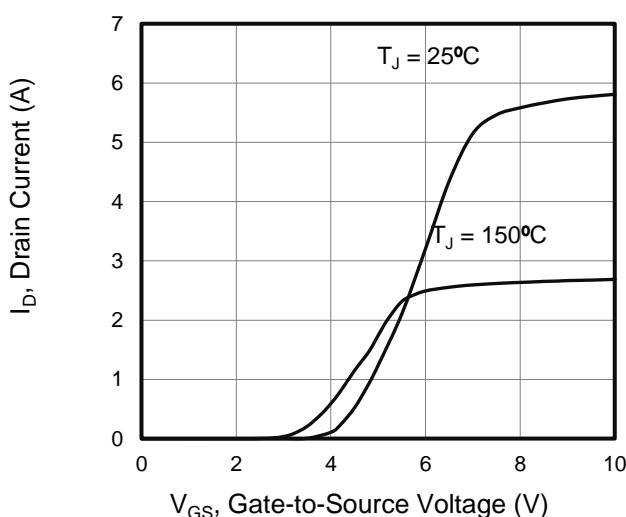
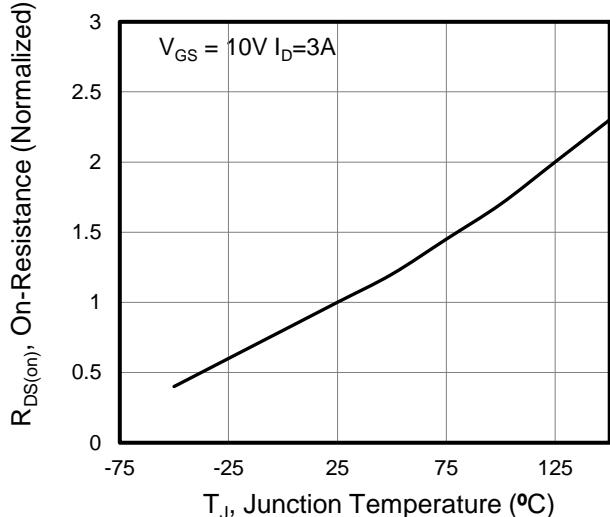


Figure 6. On-Resistance vs. Temperature



N-Channel Enhancement Mode MOSFET

Figure 7. Capacitance

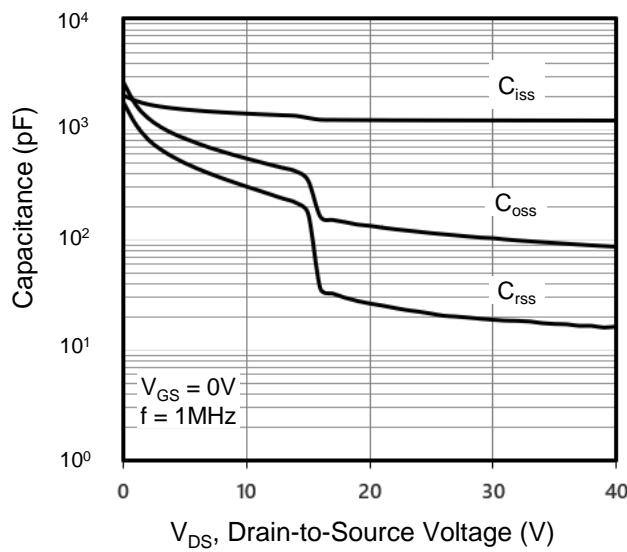


Figure 8. Gate Charge

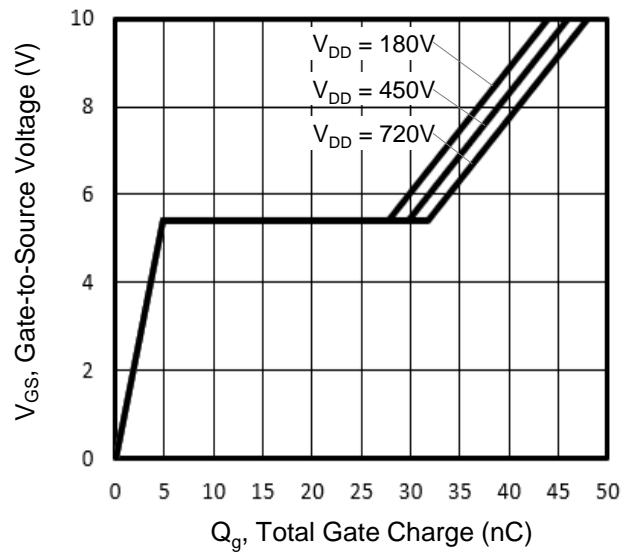
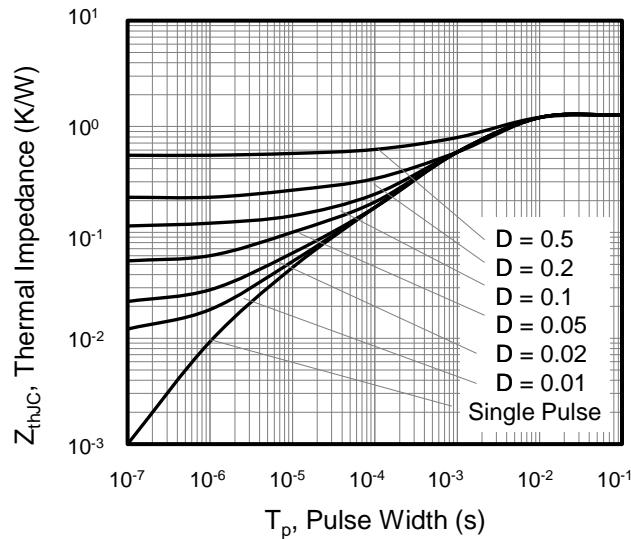
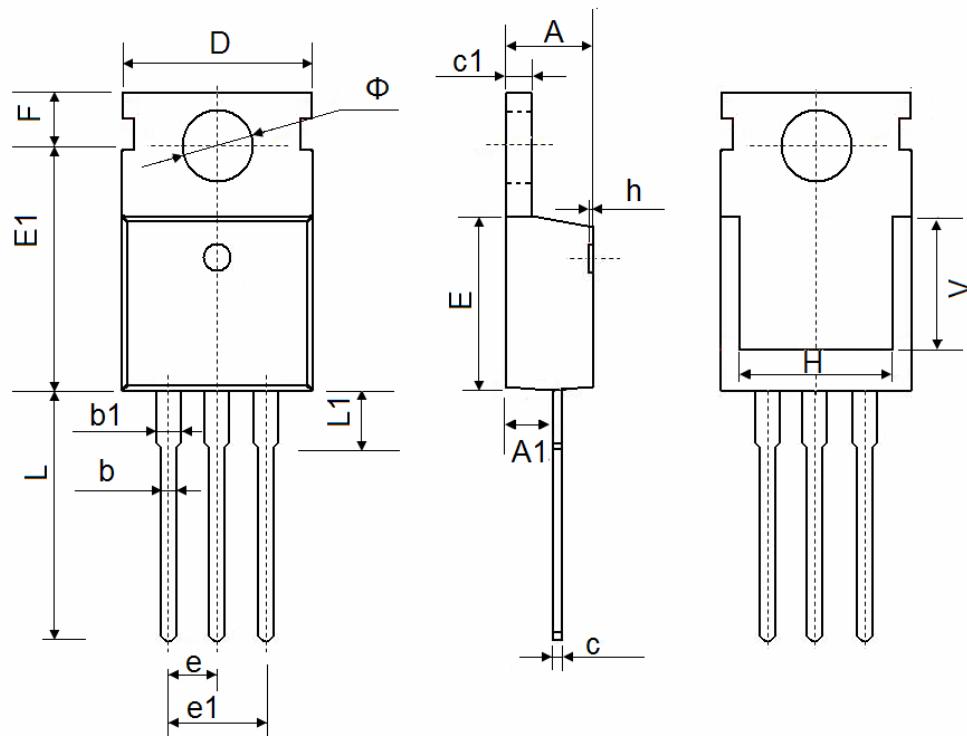


Figure 9. Transient Thermal Impedance



N-Channel Enhancement Mode MOSFET

TO-220 Package Outline Data



| Symbol | Dimensions In Millimeters | |
|--------|---------------------------|--------|
| | Min. | Max. |
| A | 4.350 | 4.650 |
| A1 | 2.250 | 2.550 |
| b | 0.710 | 0.910 |
| b1 | 1.170 | 1.400 |
| c | 0.330 | 0.650 |
| c1 | 1.200 | 1.400 |
| D | 9.910 | 10.250 |
| E | 8.9500 | 9.750 |
| E1 | 12.650 | 12.950 |
| e | 2.540 TYP. | |
| e1 | 4.980 | 5.180 |
| F | 2.650 | 2.950 |
| H | 7.900 | 8.100 |
| h | 0.000 | 0.300 |
| L | 12.700 | 13.500 |
| L1 | 2.850 | 3.250 |
| V | 7.500 REF. | |
| Φ | 3.400 | 3.800 |